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Dag Johansen

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application for:

Steven Teig, et al.

Serial No.: <not assigned yet>

Filing Date: <not assigned yet>

For: METHOD AND ARRANGEMENT FOR
LAYOUT AND MANUFACTURE OF
GRIDLESS NON MANHATTAN
SEMICONDUCTOR INTEGRATED
CIRCUITS

Examiner: <not assigned yet>

Group Art Unit: <not assigned yet>

PRELIMINARY AMENDMENT

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Sir:

Please amend the above-identified patent application as follows before examining the claims. This Preliminary Amendments is concurrently filed with the above-entitled application, which is a continuation application of a presently pending application entitled "Method And Arrangement For Layout And Manufacture Of Gridless Non Manhattan Semiconductor Integrated Circuits," filed on 6/3/01. **Applicants**

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